WHAT IS CLAIMED IS:

1. A sealable sheet for sealing an electronic element, comprising:

a first layer and a second layer sequentially toward one side in a thickness direction, the first layer being in contact with the electronic element and the second layer being exposed outwardly when sealing the electronic element, wherein

the first layer and the second layer have thermosetting properties,

an other-side surface in the thickness direction of the first layer is harder than a one-side surface in the thickness direction of the second layer at 90°C, wherein a recessed amount formed on the harder other-side surface in the thickness direction of the first layer is smaller than a recessed amount formed on the one-side surface in the thickness direction of the second layer in an iron ball drop test at 90°C, and

a push-in elastic modulus at 25°C of the second layer after thermal curing is larger than a push-in elastic modulus at 25°C of the first layer after thermal curing.

2. The sealable sheet according to claim 1, wherein

a push-in elastic modulus at 25°C of the second layer before thermal curing is smaller than a push-in elastic modulus at 25°C of the first layer before thermal curing.

3. The sealable sheet according to claim 1 or 2, wherein

the first layer contains a first organic component containing a first thermosetting resin and a first thermoplastic resin,

the second layer contains a second organic component containing a second thermosetting resin and a second thermoplastic resin, and

a mass ratio of the second thermoplastic resin to the second organic component is smaller than a mass ratio of the first thermoplastic resin to the first organic component.